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CHUANG(10) **Pub. No.: US 2023/0230959 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **SEMICONDUCTOR PACKAGE STRUCTURE
AND METHOD FOR PREPARING SAME**(71) Applicant: **CHANGXIN MEMORY
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ABSTRACT

A semiconductor package structure and a method for preparing the same are provided. The semiconductor package structure includes: a substrate; a first semiconductor chip located on the substrate, the first semiconductor chip having a first surface that is bare and the first surface having a silicon-containing surface; second semiconductor chip structures located on the first surface of the first semiconductor chip, the second semiconductor chip structures having second surfaces opposite to the first surface; a first package compound structure having a joint surface, the joint surface covering at least the first surface of the first semiconductor chip and the second surfaces of the second semiconductor chip structures. The joint surface has a silicon-containing surface.

